



Docket No.: M4065.0468/P468-B

(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Phillip E. Byrd et al.

Application No.: 10/649,781

Confirmation No.: 5845

Filed: August 28, 2003

Art Unit: 2812

For: METHOD FOR TEMPORARILY ISOLATING

A DIE FROM A COMMON CONDUCTOR TO FACILITATE WAFER LEVEL TESTING

Examiner: S. D. Isaac

## RESPONSE TO NON-COMPLIANT AMENDMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

## **INTRODUCTORY COMMENTS**

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.